



IFX Day 2021

Capital Markets Day
virtual format, 5 October 2021



IFX Day 2021 – Agenda

UK Time	Topic	Presenters
14:00 – 14:05	Welcome address	Alexander Foltin (IR)
14:05 – 14:35	1. The Big Picture	Reinhard Ploss; Sven Schneider
14:35 – 15:20	2. Electrification	Jochen Hanebeck; Constanze Hufenbecher; Peter Schiefer; Andreas Urschitz; Peter Wawer
15:20 – 15:30	Coffee break	
15:30 – 16:15	3. Digitalization	Helmut Gassel; Constanze Hufenbecher; Thomas Rosteck; Peter Schiefer; Andreas Urschitz
16:15 – 16:45	4. Value Creation	Sven Schneider; Jochen Hanebeck; Thomas Rosteck; Peter Schiefer; Andreas Urschitz; Peter Wawer
16:45 – 17:25	Joint Q&A	Moderated by Alexander Foltin (IR)
17:25 – 17:30	Wrap-up & farewell address	Reinhard Ploss

Key messages

Semiconductors ever more pervasive – Infineon is uniquely positioned

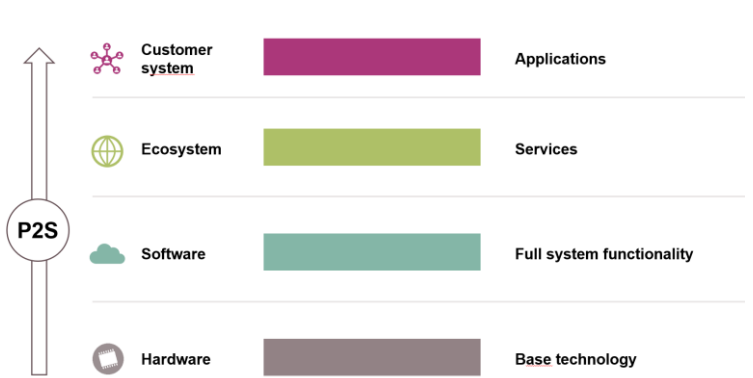
Electrification

- › CO₂ saving
- › Energy efficiency
- › Cost saving

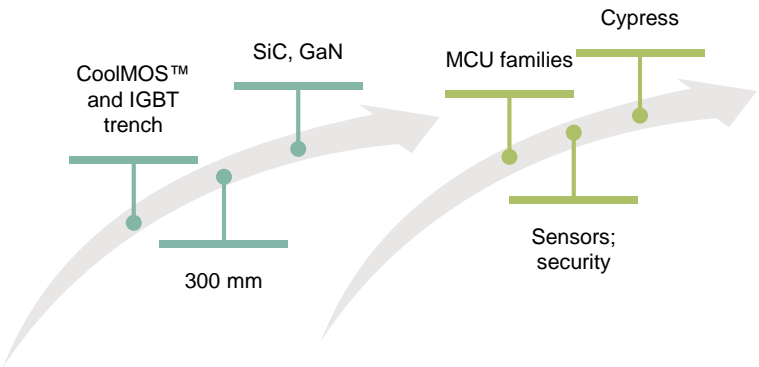
Digitalization

- › Productivity
- › Comfort
- › New use cases

P2S guiding our journey – from technology to solution provider



Long-term perspective paying off – capacity expansion underway, WBG focus



ESG: part of the solution – CO₂ neutrality by 2030



Cyclical and structural winner – xEV, renewables leaders; at the core of IoT



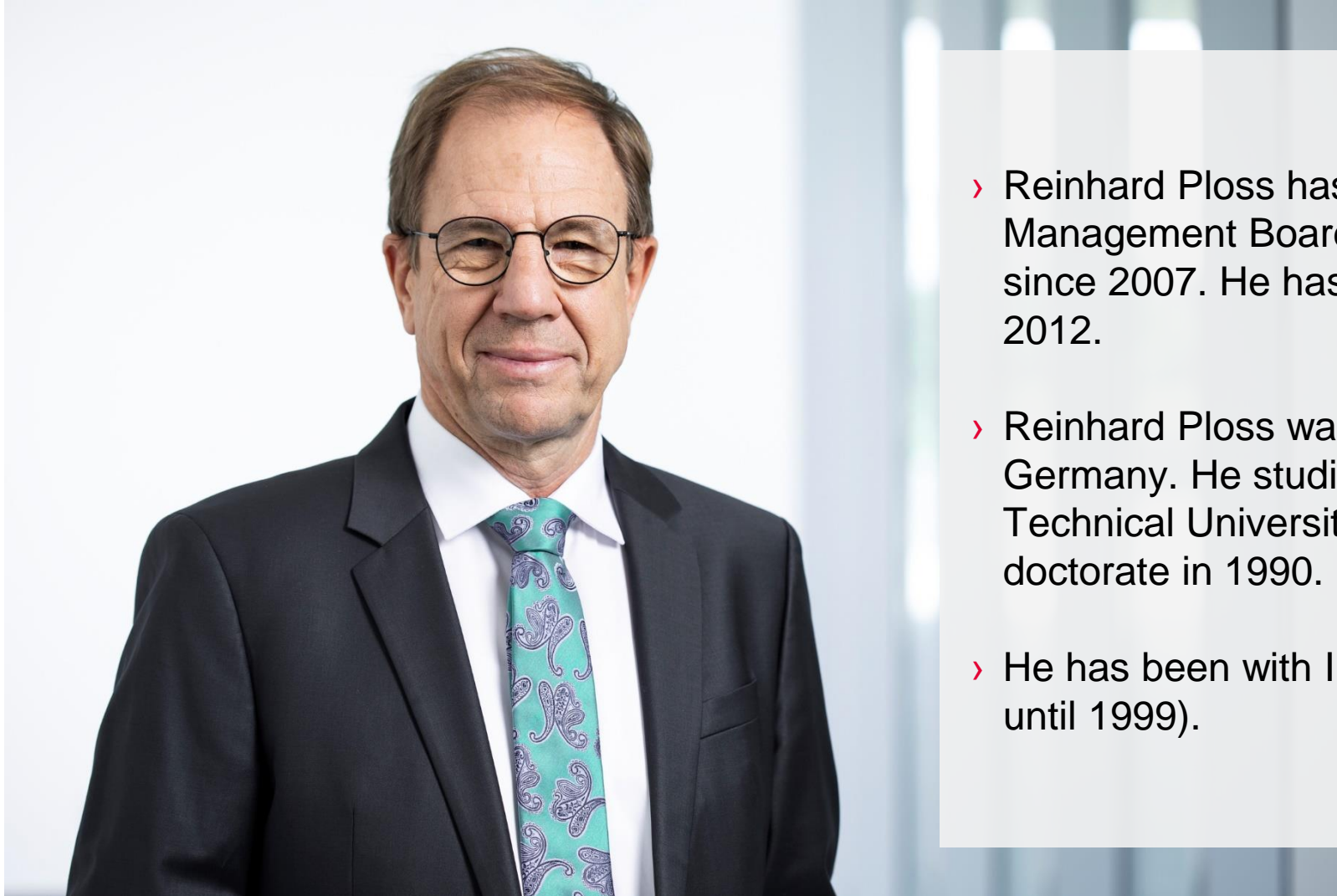
Sustainable value creation – profitable growth journey continues

	TOM
Revenue growth	9%+
Segment Result Margin	19%
Investment-to-sales	13%



Part of your life. Part of tomorrow.

Dr. Reinhard Ploss



- › Reinhard Ploss has been a member of the Management Board of Infineon Technologies AG since 2007. He has been CEO since 1 October 2012.
- › Reinhard Ploss was born in 1955 in Bamberg, Germany. He studied process engineering at the Technical University of Munich and received his doctorate in 1990.
- › He has been with Infineon since 1986 (Siemens AG until 1999).

Dr. Helmut Gassel



- › Helmut Gassel has been a member of the Management Board and Chief Marketing Officer of Infineon Technologies AG since 2016.
- › Helmut Gassel was born in 1964 in Dortmund, Germany. He holds a Diploma in Physics from the Ruhr-University in Bochum, Germany. He received his PhD in Electrical Engineering from the University Duisburg, Germany.
- › He has been with Infineon since 1995 (Siemens AG until 1999).

Jochen Hanebeck



- › Jochen Hanebeck has been a member of the Management Board of Infineon Technologies AG and Chief Operations Officer since 2016.
- › Jochen Hanebeck was born in 1968 in Dortmund, Germany. He received a degree in electrical engineering from RWTH Aachen University, Germany.
- › He has been with Infineon since 1994 (Siemens AG until 1999).

Constanze Hufenbecher



- › Constanze Hufenbecher has been a member of the Management Board of Infineon Technologies AG and Chief Digital Transformation Officer since 2021.
- › Constanze Hufenbecher was born in 1970 in Albstadt, Germany. She graduated in Business Administration from the University of Tübingen, Germany.
- › Her career included positions at VIAG AG (1994 – 1997), Bertelsmann AG (1998 – 2002), Infineon Technologies AG (2004 – 2009), and Lufthansa Technik AG (2016 – 2020, CFO).

Dr. Sven Schneider



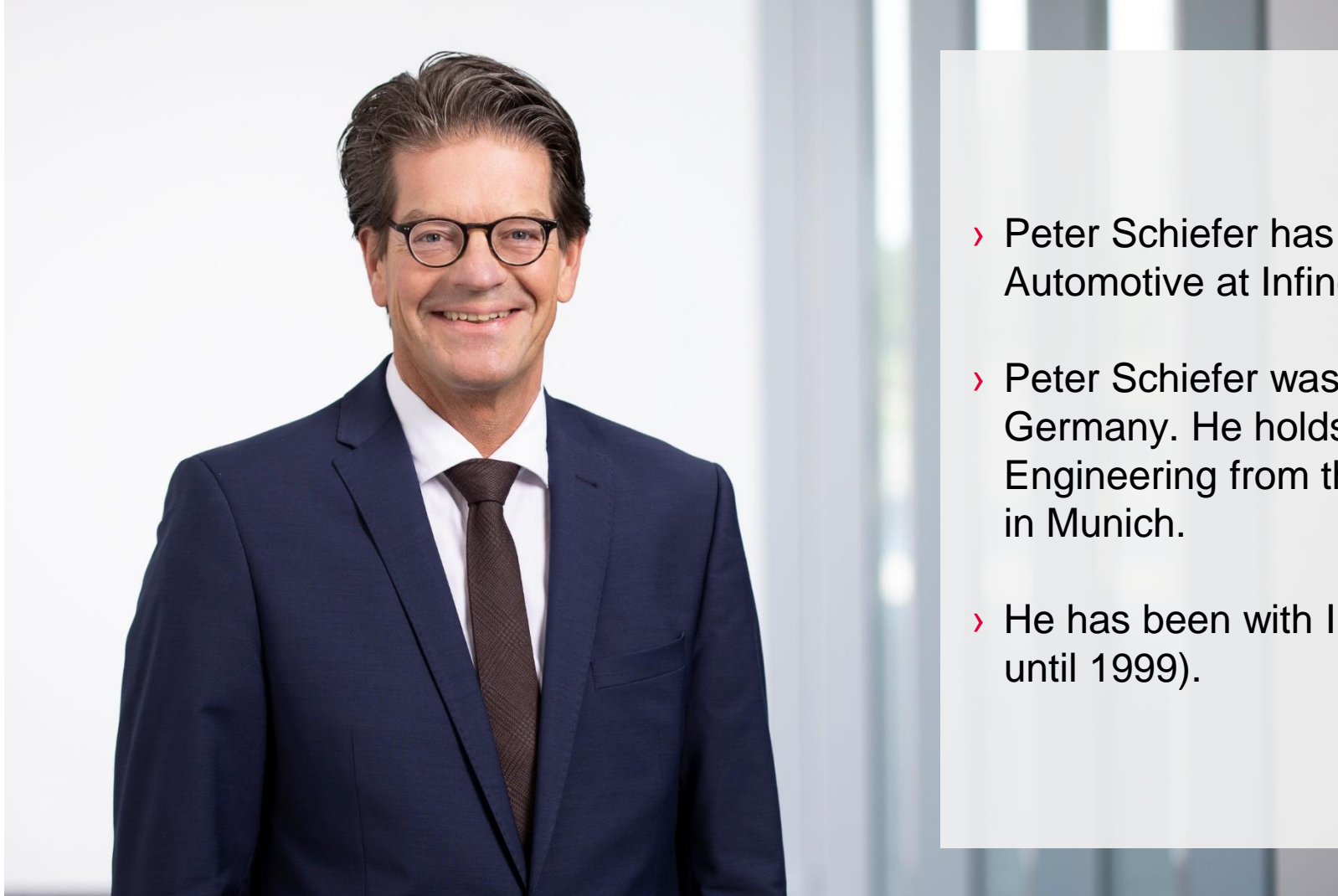
- › Sven Schneider has been a member of the Management Board of Infineon Technologies AG and Chief Financial Officer since 2019.
- › Sven Schneider was born in 1966 in Berlin. After completing his studies of Business Administration (Diplom-Kaufmann), he received his doctorate in Business Administration from the University of Trier, Germany.
- › From 1995 to 2019, he has held several positions at Linde AG, most recently as Spokesman of the Executive Board, Chief Financial Officer and Labor Director.

Thomas Rosteck



- › Thomas Rosteck has been the Division President Connected Secure Systems at Infineon Technologies AG since 2017 (Chip Card & Security at that time).
- › Thomas Rosteck was born in 1966 in Offenbach am Main, Germany. He graduated in Business Administration and Computer Science from the Technical University of Darmstadt, Germany.
- › He has been with Infineon since 1998 (Siemens AG until 1999).

Peter Schiefer



- › Peter Schiefer has been the Division President Automotive at Infineon Technologies AG since 2016.
- › Peter Schiefer was born in 1965 in Munich, Germany. He holds a Diploma in Electrical Engineering from the University of Applied Sciences in Munich.
- › He has been with Infineon since 1990 (Siemens AG until 1999).

Dr. Peter Wawer



- › Peter Wawer has been the Division President Industrial Power Control at Infineon Technologies AG since 2016.
- › Peter Wawer was born in 1967 in Berlin. He holds a Diploma in Electrical Engineering from the Technical University in Berlin where he also received his PhD.
- › He has been with Infineon since 1997 (Siemens AG until 1999).

Andreas Urschitz



- › Andreas Urschitz has been the Division President Power & Sensor Systems at Infineon Technologies AG since 2012 (Power Management & Multimarkets at that time).
- › Andreas Urschitz was born in 1972 in Klagenfurt, Austria. He holds a master's degree in Commercial Science from the Vienna University of Economics and Business, Austria.
- › He has been with Infineon since 1995 (Siemens AG until 1999).

Glossary (1 of 2)

ABS	anti-blocking system
AC	alternating current
AC-DC	alternating current - direct current
AD	automated driving
ADAS	advanced driver assistance system
AI	artificial intelligence
AM	amplitude modulation
AR	augmented reality
ASIC	application-specific integrated circuit
ATV	Automotive division
BEV	battery electric vehicle
BIOS	basic input output system
BLE	Bluetooth Low Energy
BMS	battery management system
BoM	bill of material
BPA	battery-powered applications
BT	Bluetooth
CMOS	complementary metal-oxide semiconductor
CPU	central processing unit
CSS	Connected Secure Systems division
CY	Cypress

DC	direct current
DC-DC	direct current - direct current
Edge AI	edge artificial intelligence
EPS	electric power steering
eSIM	embedded subscriber identity module
EV	electric vehicle
FAE	field application engineer
FHEV	full hybrid electric vehicle
FPGA	field programmable gate array
G2M	go-to-market
GaN	gallium nitride
GPU	graphics processing unit
HEMT	high electron mobility transistor
HEV	mild and full hybrid electric vehicle
HMI	human machine interaction
HW	hardware
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	Internet of Things
IPC	Industrial Power Control division

Glossary (2 of 2)

IPM	intelligent power module
IRF	International Rectifier
LTM	last twelve months
MCU	microcontroller unit
MEMS	micro electro-mechanical systems
MHEV	mild hybrid electric vehicle
mild-hybrid	vehicles using start-stop systems, recuperation, DC-DC conversion, e-motor
ML	machine learning
MOSFET	metal-oxide silicon field-effect transistor
NFC	near-field communications
NOR Flash	non-volatile memory for program storage
NZE	net zero emissions
OBC	on-board charger
OEM	original equipment manufacturer
OS	operating system
P2S	Infineon's strategic product-to-system approach
PAS	photo-acoustic spectroscopy
PHEV	plug-in hybrid electric vehicle
PLC	programmable logic control
PMIC	power management IC

PSoC	programmable system-on-chip
PSS	Power & Sensor Systems division
PV	photovoltaic
RAM	random access memory
RF	radio frequency
SAAS	software-as-a-service
Si	silicon
SiC	silicon carbide
SoC	system-on-chip
SR	segment result
SW	software
ToF	time-of-flight
TOM	target operating model
UI	user interface
USB	universal serial bus
V2X	vehicle-to-everything communication
VR	virtual reality
WBG	wideband gap
Wi-Fi	wireless fidelity
xEV	all degrees of vehicle electrification (EV, HEV, PHEV)

ESG footnotes and disclaimer

- 1) This figure considers manufacturing, transportation, function cars, flights, materials, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. and is based on internally collected data and externally available conversion factors. All data relate to the 2020 fiscal year. Manufacturing service providers are not included.
- 2) This figure is based on internally established criteria, which are explained in the explanatory notes. The figure relates to the calendar year 2019 and considers the following fields of application: automotive, LED, induction cookers, server, renewable energy (wind, photovoltaic), mobile phone chargers as well as drives. CO₂ savings are calculated on the basis of potential savings of technologies in which semiconductors are used. The CO₂ savings are allocated on the basis of Infineon market share, semiconductor content and lifetime of the technologies concerned, based on internal and external experts' estimations.

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